# MA2SD300G

## Silicon epitaxial planar type

For super high speed switching

### ■ Features

- Small reverse current:  $I_R < 2 \mu A$  (at  $V_R = 30 \text{ V}$ )
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	$V_R$	30	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V	
Forward current (Average)	I <sub>F(AV)</sub>	100	mA	
Peak forward current	I <sub>FM</sub>	200	mA	
Non-repetitive peak forward	I <sub>FSM</sub>	1	A	
surge current *				
Junction temperature	$T_{j}$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

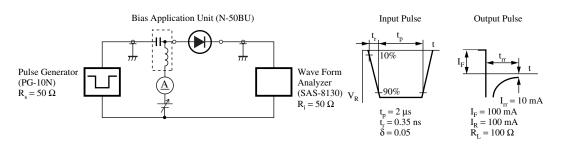
### Package

- Code
  - SSMini2-F4
- Pin Name
  - 1: Anode
- 2: Cathode
- Marking Symbol: 8N

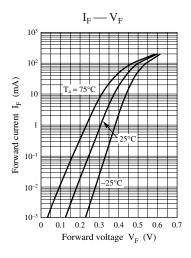
## ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

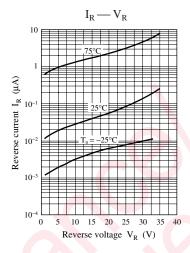
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 10 \text{ mA}$		0.38	0.44	V
	V <sub>F2</sub>	$I_F = 100 \text{ mA}$	00	0.51	0.58	
Reverse current	$I_{R1}$	$V_R = 10 \text{ V}$		).	0.3	μΑ
	$I_{R2}$	$V_R = 30 \text{ V}$	1.90		2	
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		9		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

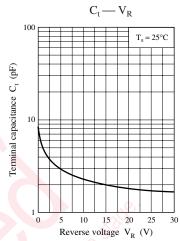
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Absolute frequency of input and output is 250 MHz
  - 4. \*: t<sub>rr</sub> measurement circuit

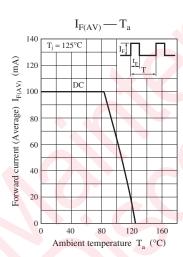


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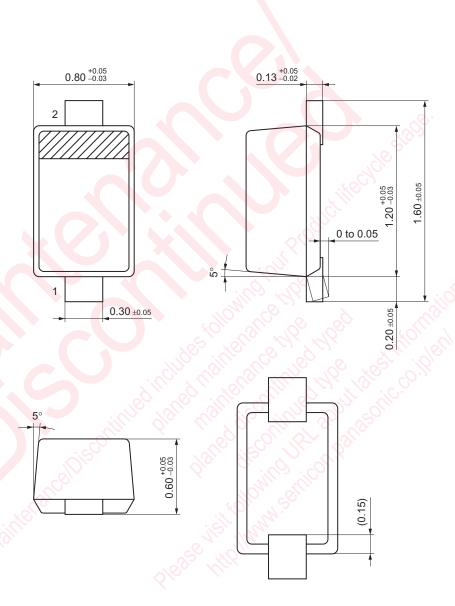






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SSMini2-F4 Unit: mm



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